

Title (en)

HEATING ASSEMBLY AND AEROSOL FORMING DEVICE

Title (de)

HEIZANORDNUNG UND AEROSOLERZEUGUNGSVORRICHTUNG

Title (fr)

ENSEMBLE DE CHAUFFAGE ET DISPOSITIF DE FORMATION D'AÉROSOL

Publication

**EP 4218444 A1 20230802 (EN)**

Application

**EP 21870731 A 20210323**

Priority

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- CN 2021082418 W 20210323

Abstract (en)

The present application provides a heater assembly and an aerosol-forming device. The heater assembly includes a heating body. The heating body is configured to be inserted into and to heat an aerosol-forming substrate. The heating body includes a first segment portion and a second segment portion spaced apart from the first segment portion, the second segment portion is connected to an end of the first segment portion. At least a portion of the first segment portion and at least a portion of the second segment portion are configured to be inserted into the aerosol-forming substrate and to generate heat, when being supplied with power, to heat the aerosol-forming substrate. The heating body in the heater assembly can be directly inserted into the aerosol-forming substrate and is highly stable. Further, the heating body may heat the aerosol-forming substrate more uniformly.

IPC 8 full level

**A24F 40/46** (2020.01); **A24F 47/00** (2020.01)

CPC (source: CN EP KR)

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